



Printed Function Sensors and Materials

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Message from the Guest Editor

In the era of the 4th Industrial Revolution, the printed electronics market is gradually expanding, and the advantages of printed electronic sensors are highlighted by grafting with existing sensing technologies as well as IoT (Internet of Things) systems and smart packaging.

This Special Issue focuses on research to produce a variety of functional sensors using a printing or roll-to-roll process. It accepts materials with original and creative research findings and review articles related to printed functional sensors and allows readers to learn more about the technology associated with their availability to help everyone.

Therefore, we welcome articles that report the latest technology on sensor materials, concepts, fabrication and testing technology, printing on new substrates and application-oriented print sensor systems, and closely related topics.

- printed functional sensor
- flexible/stretchable substrate
- inkjet printing
- screen printing
- gravure printing
- EHD printing
- roll-to-roll technology
- wearable devices
- smart packaging
- IoT technology





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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